

QH8JA1

# -20V Pch +Pch Middle Power MOSFET

## Datasheet

V <sub>DSS</sub>	-20V
R <sub>DS(on)</sub> (Max.)	38mΩ
Ι <sub>D</sub>	±5.0A
P <sub>D</sub>	1.5W

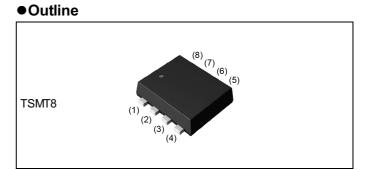
## Features

- 1) Low on resistance.
- 2) Small surface mount package(TSMT8)
- 3) -1.8V Drive.

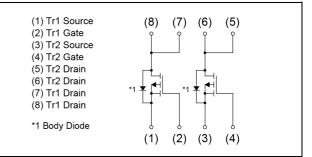
Application

Switching

4) Pb-free lead plating ; RoHS compliant



#### Inner circuit



#### Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TCR
	Marking	JA1

#### ● Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified) <Tr1 and Tr2>

Parameter	Symbol	Value	Unit		
Drain - Source voltage	V <sub>DSS</sub>	-20	V		
Continuous drain current	I <sub>D</sub> *1	±5.0	A		
Pulsed drain current	I_DP <sup>*2</sup>	±18	A		
Gate - Source voltage	V <sub>GSS</sub>	±10	V		
Avalanche current, single pulse	I <sub>AS</sub> *3	-5.0	A		
Avalanche energy, single pulse	E <sub>AS</sub> *3	8.9	mJ		
Dower discipation (total)	P <sub>D</sub> <sup>*4</sup>	1.5	10/		
Power dissipation (total)	P <sub>D</sub> *5	1.1	W		
Junction temperature	Tj	150	°C		
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C		

#### •Thermal resistance

Deremeter	Symbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres innotion embient (total)	$R_{thJA}^{*4}$	-	-	83.3	°C/W
Thermal resistance, junction - ambient (total)	$R_{thJA}^{*5}$	-	-	113	

## •Electrical characteristics (T<sub>a</sub> = 25°C) <Tr1 and Tr2>

Deveneter	O mah al	Conditions		Values			
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -1mA	-20	-	-	V	
Breakdown voltage	ΔV <sub>(BR)DSS</sub>	I <sub>D</sub> = -1mA		-10.3		mV/°C	
temperature coefficient	ΔTj	referenced to 25°C	-	-10.5	-	mv/ C	
Zero gate voltage $I_{DSS}$ $V_{DS}$ = -20V, $V_{GS}$ = 0V		-	-	-1	μA		
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±10V	-	-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -1mA$	-0.5	-	-1.2	V	
Gate threshold voltage	$\Delta V_{GS(th)}$	I <sub>D</sub> = -1mA		47			
temperature coefficient	ΔTj	referenced to 25°C	-	1.7	-	mV/°C	
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -5.0A	-	28	38		
Static drain - source on - state resistance	R <sub>DS(on)</sub> *6	V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -5.0A	-	35	48	mΩ	
		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -1.2A	-	49	77		
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	11	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *6	V <sub>DS</sub> = -5V, I <sub>D</sub> = -5A	5.5	-	-	S	

\*1 Vgs≧2.5V

\*2 Pw $\leq$ 10µs , Duty cycle $\leq$ 1%

\*3 L  $\simeq$  0.5mH, V\_{DD} = -10V, R\_G = 25 $\Omega$ , STARTING T\_i = 25°C Fig.3-1,3-2

\*4 Mounted on a ceramic board (30×30×0.8mm)

- \*5 Mounted on a FR4 (25×25×0.8mm)
- \*6 Pulsed



# •Electrical characteristics ( $T_a = 25^{\circ}C$ ) <Tr1 and Tr2>

Deremeter	Cumphal	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	720	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = -10V	-	140	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	125	-		
Turn - on delay time	t <sub>d(on)</sub> *6	$V_{DD} \simeq -10V, V_{GS} = -4.5V$	-	11	-		
Rise time	t <sub>r</sub> *6	I <sub>D</sub> = -2.5A	-	32	-		
Turn - off delay time	$t_{d(off)}^{*6}$	$R_L = 4\Omega$	-	70	-	ns	
Fall time	t <sub>f</sub> *6	R <sub>G</sub> = 10Ω	-	65	-		

# •Gate charge characteristics ( $T_a = 25^{\circ}C$ ) <Tr1 and Tr2>

Deremeter	Cumphel	Conditions	Values			1 1
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q <sub>g</sub> *6		-	10.2	-	
Gate - Source charge	$Q_{gs}^{*6}$	V <sub>DD</sub> ≃ -10V, I <sub>D</sub> = -5.0A V <sub>GS</sub> = -4.5V	-	1.3	-	nC
Gate - Drain charge	Q <sub>gd</sub> *6		-	3.4	-	

# •Body diode electrical characteristics (Source-Drain) ( $T_a = 25^{\circ}C$ )

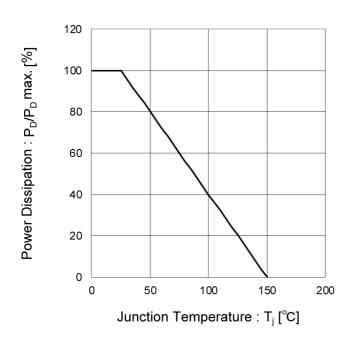
<Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit	
	Symbol Conditions		Min.	Тур.	Max.	Offic	
Continuous forward current	۱ <sub>s</sub>	T - 25°0	-	-	-1.0	•	
Pulse forward current	$I_{SP}^{*2}$	T <sub>a</sub> = 25°C	-	-	-18	A	
Forward voltage	$V_{SD}^{*6}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A	-	-	-1.2	V	

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#### Electrical characteristic curves



## Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

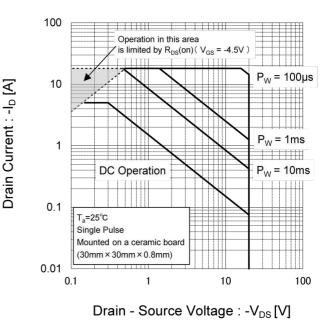
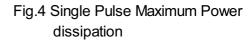
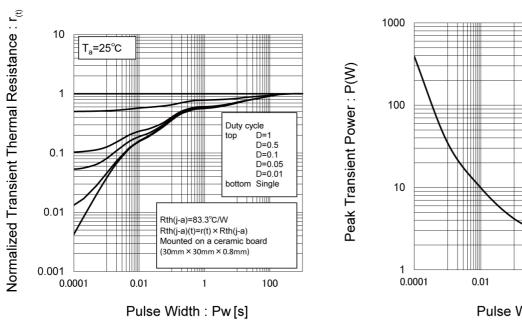
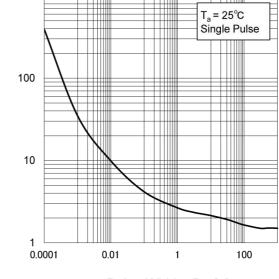


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



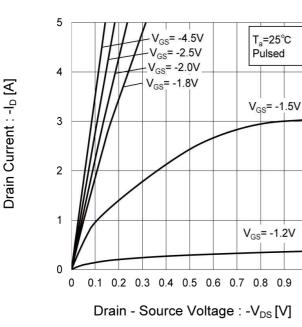




Pulse Width : Pw [s]

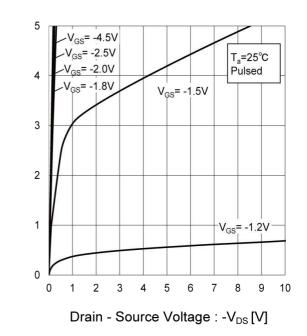


#### • Electrical characteristic curves



## Fig.5 Typical Output Characteristics(I)

## Fig.6 Typical Output Characteristics(II)

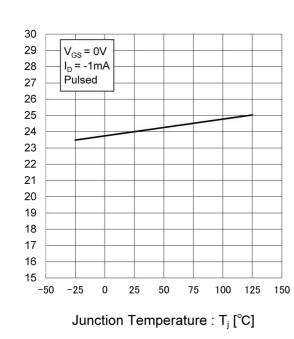


Drain Current : -I<sub>D</sub> [A]

1

## Fig.7 Breakdown Voltage vs. Junction Temperature

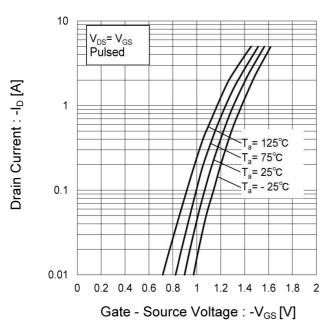
Drain-Source Breakdown Voltage : -V<sub>(BR)DSS</sub> [V]



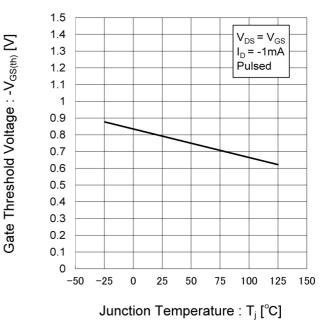
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#### • Electrical characteristic curves

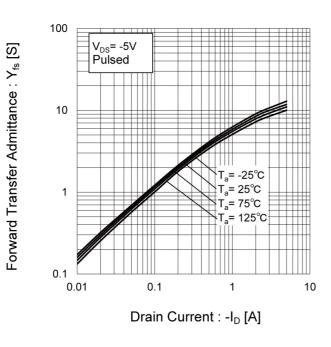


# Fig.8 Typical Transfer Characteristics



#### Fig.9 Gate Threshold Voltage vs. Junction Temperature

## Fig.10 Forward Transfer Admittance vs. Drain Current





## • Electrical characteristic curves

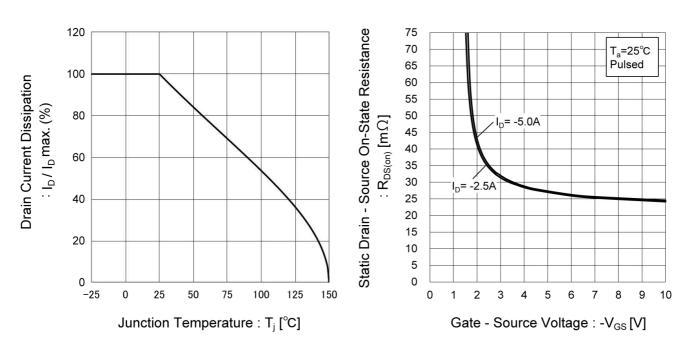
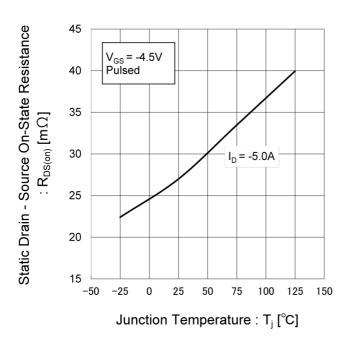


Fig.11 Drain Current Derating Curve

## Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





## •Electrical characteristic curves

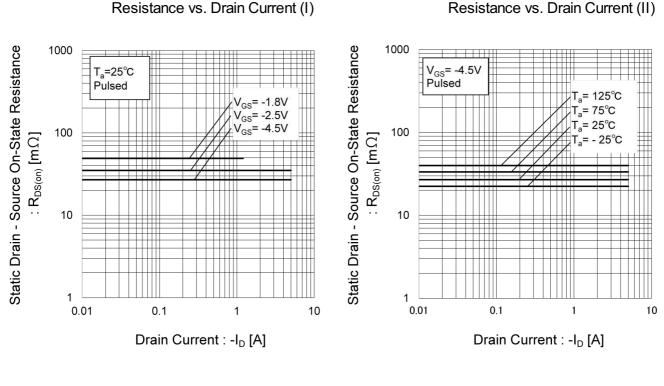


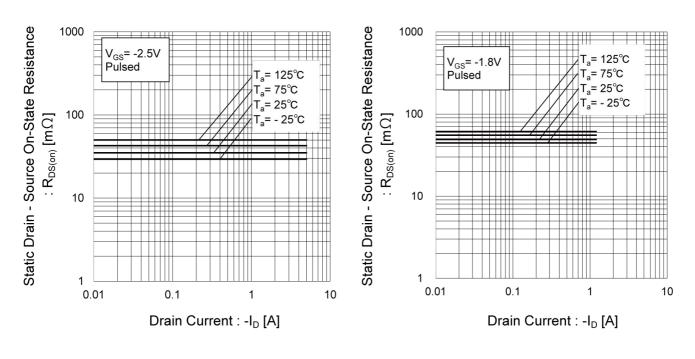
Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

Fig.16 Static Drain - Source On - State

Resistance vs. Drain Current (III)

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)

Fig.15 Static Drain - Source On - State



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#### •Electrical characteristic curves

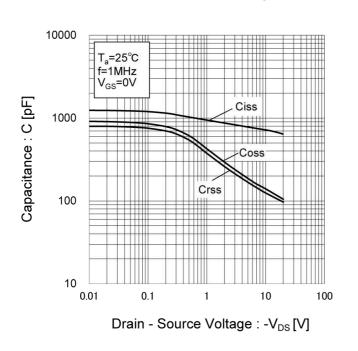


Fig.18 Typical Capacitance vs.

Drain - Source Voltage

## Fig.19 Switching Characteristics

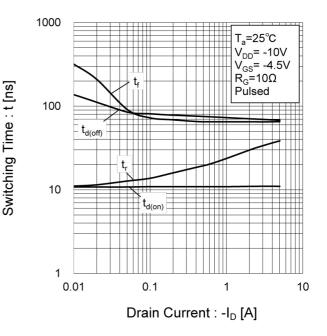


Fig.20 Dynamic Input Characteristics

Gate - Source Voltage : -V<sub>GS</sub> [V]

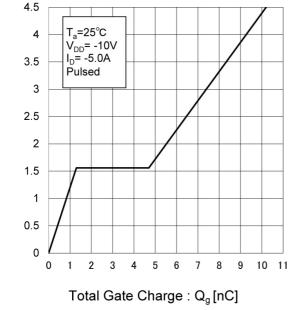
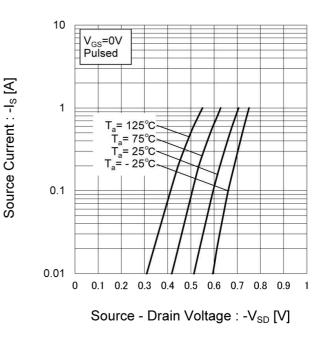


Fig.21 Source Current vs. Source Drain Voltage



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# •Measurement circuits <It is the same for the Tr1 and Tr2>



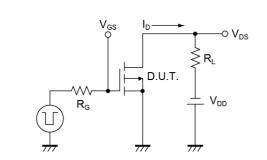


Fig.2-1 Gate Charge Measurement Circuit

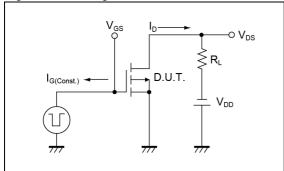


Fig.3-1 Avalanche Measurement Circuit

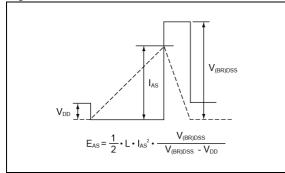


Fig.1-2 Switching Waveforms

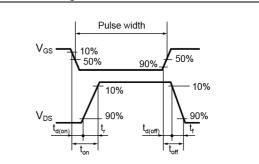
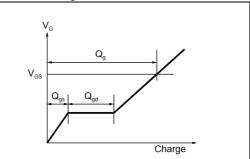
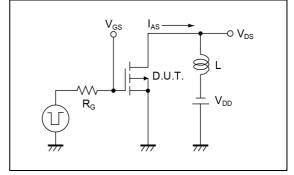


Fig.2-2 Gate Charge Waveform



#### Fig.3-2 Avalanche Waveform

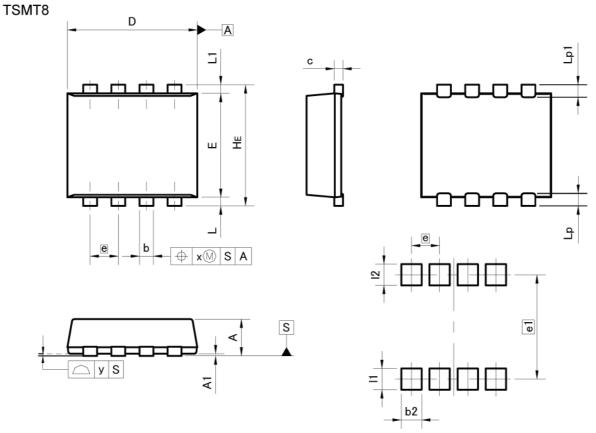


## Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INC	HES
	MIN	MAX	MIN	MAX
A	0.75	0.85	0.030	0.033
A1	0.00	0.05	0.000	0.002
b	0.27	0.37	0.011	0.015
с	0.12	0.22	0.005	0.009
D	2.90	3.10	0.114	0.122
E	2.30	2.50	0.091	0.098
е	0.65		0.026	
HE	2.70	2.90	0.106	0.114
L	0.10	0.30	0.004	0.012
L1	0.10	0.30	0.004	0.012
Lp	0.19	0.39	0.007	0.015
Lp1	0.19	0.39	0.007	0.015
x	8 <del>55</del>	0.10	8 <del></del> )	0.004
v	0.77	0.10	1.00	0.004

DIM	MILIM	ETERS	INCHES	
	MIN	MAX	MIN	MAX
b2	1. <del>14</del>	0.47	-	0.019
e1	2.41		0.0	095
11	10 <del>10</del>	0.49	-	0.019
12	8 <del></del>	0.49	á <del>lat</del> a	0.019

Dimension in mm/inches



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CLASSⅣ	CLASSII	CLASSⅢ	CLASSII

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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